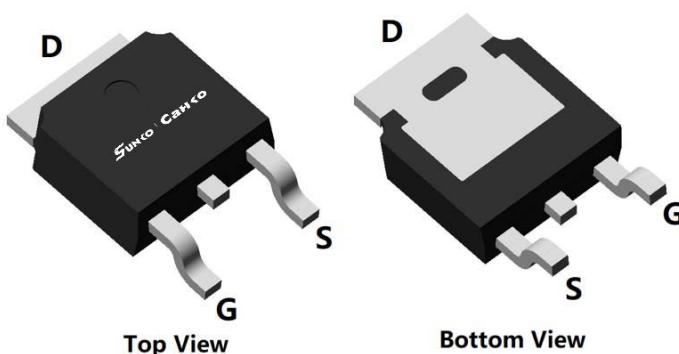
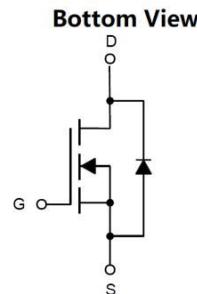


## N-Channel Enhancement Mode Field Effect Transistor



TO-252



### Product Summary

- $V_{DS}$  30V
- $I_D$  80A
- $R_{DS(ON)}$  (at  $V_{GS} = 10V$ ) <4.9mohm
- $R_{DS(ON)}$  (at  $V_{GS} = 4.5V$ ) <7.0mohm
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- High current load applications
- Load switch
- Hard switched and high frequency circuits
- Uninterruptible power supply

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	30	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current	$T_c=25^\circ\text{C}$	$I_D$	80	A
	$T_c=100^\circ\text{C}$		50	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	190	A
Single Pulse Avalanche Energy <sup>B</sup>		$E_{AS}$	100	mJ
Total Power Dissipation <sup>C</sup>	$T_c=25^\circ\text{C}$	$P_D$	38	W
	$T_c=100^\circ\text{C}$		15	W
Thermal Resistance Junction-to-Ambient <sup>D</sup>		$R_{\theta JA}$	60	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	3.3	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	°C

### Ordering Information (Example)

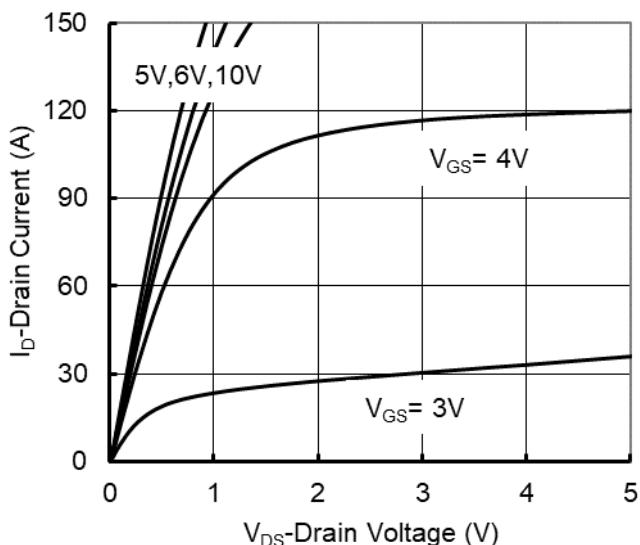
PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCD80N03B	F1/F2	SCD80N03B	2500	/	25000	13" reel

■ Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

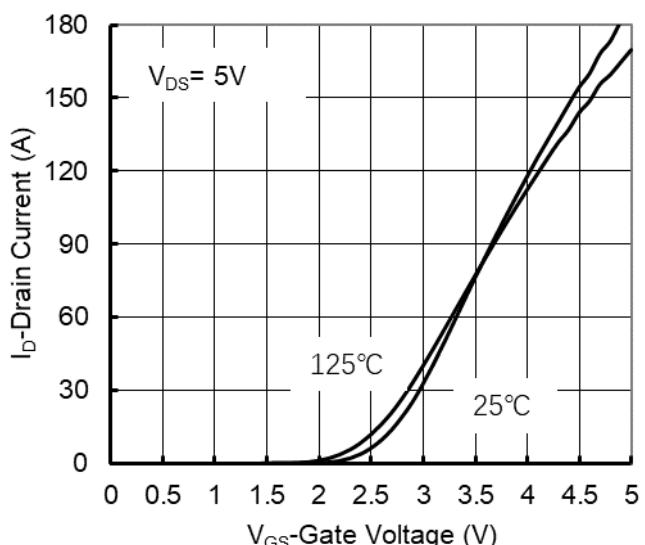
Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$		3.4	4.9	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=15\text{A}$		5.4	7.0	
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$		0.85	1.2	V
Gate resistance	$R_{\text{G}}$	f=1MHz, Open drain	-	2.7	-	$\Omega$
Maximum Body-Diode Continuous Current	$I_{\text{S}}$				80	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		2191		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			300		
Reverse Transfer Capacitance	$C_{\text{rss}}$			247		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, I_{\text{D}}=20\text{A}$		46.3		$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$			8.8		
Gate-Drain Charge	$Q_{\text{gd}}$			9.2		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_{\text{F}}=20\text{A}, \text{di/dt}=100\text{A/us}$		1.6		$\text{ns}$
Reverse Recovery Time	$t_{\text{rr}}$			11		
Turn-on Delay Time	$t_{\text{D(on)}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=15\text{V}, R_{\text{L}}=0.75\Omega, R_{\text{GEN}}=3\Omega$		11		$\text{ns}$
Turn-on Rise Time	$t_{\text{r}}$			80		
Turn-off Delay Time	$t_{\text{D(off)}}$			39		
Turn-off fall Time	$t_{\text{f}}$			92		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B.  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{G}}=10\text{V}$ ,  $R_{\text{G}}=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=20\text{A}$ .
- C.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of  $R_{\text{GJA}}$  is measured with the device mounted on the minimum recommend pad size, in the still air environment with  $T_A=25^\circ\text{C}$ . The maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

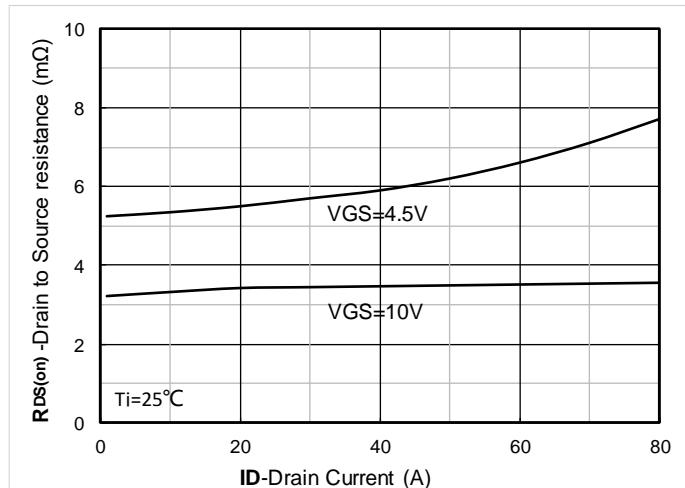
## ■ Typical Performance Characteristics



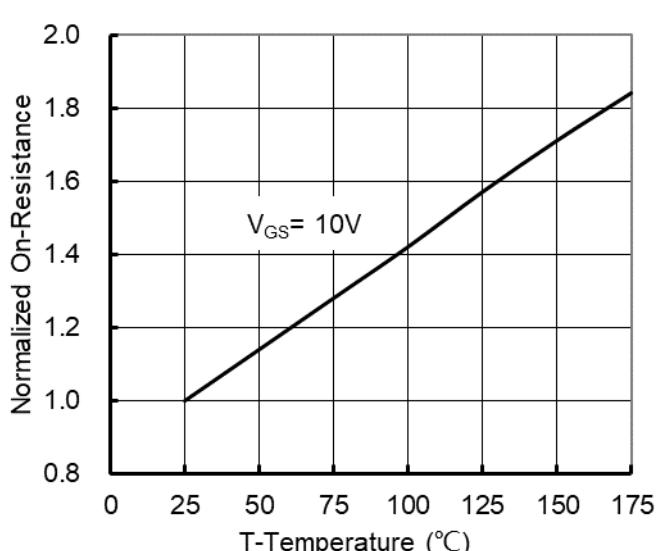
**Figure 1. Output Characteristics**



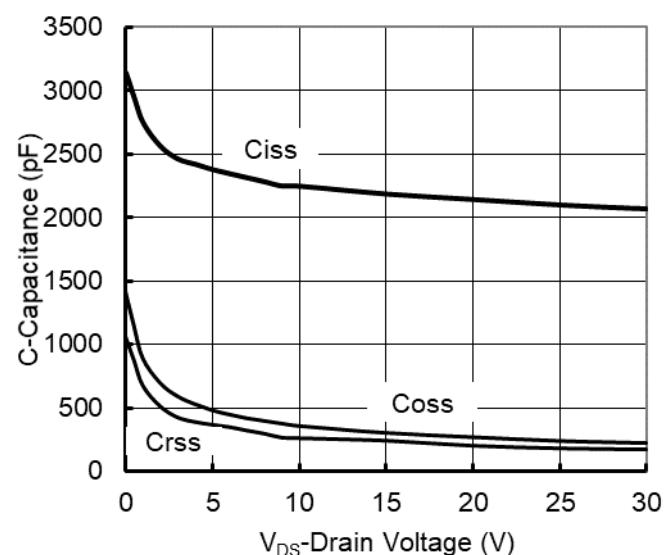
**Figure 2. Transfer Characteristics**



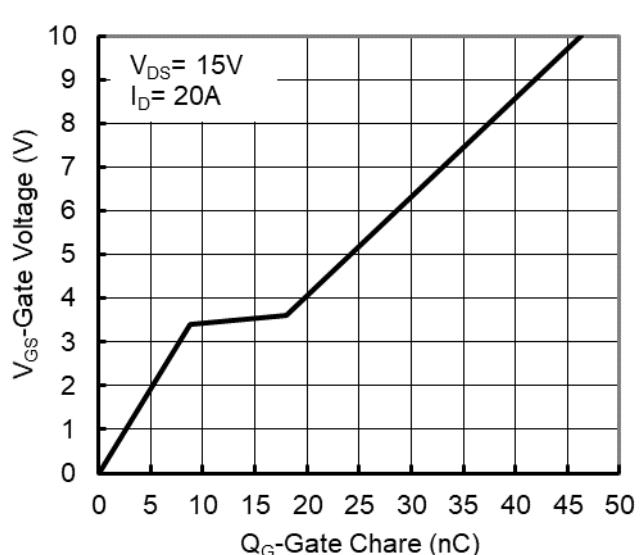
**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4. On-Resistance vs. Junction Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge**

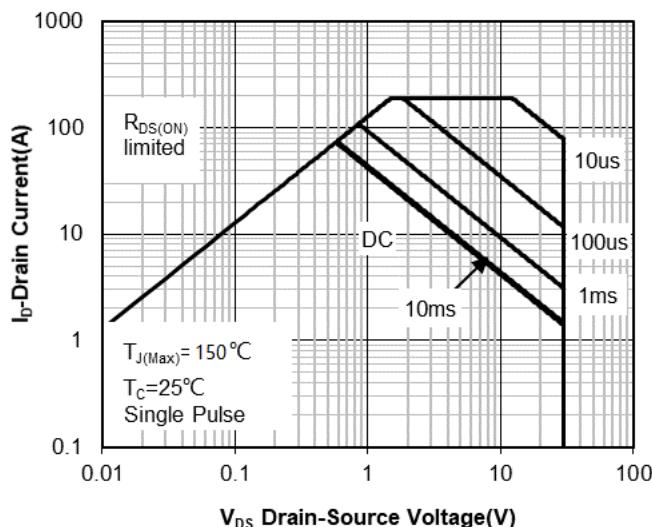


Figure 7. Safe Operation Area

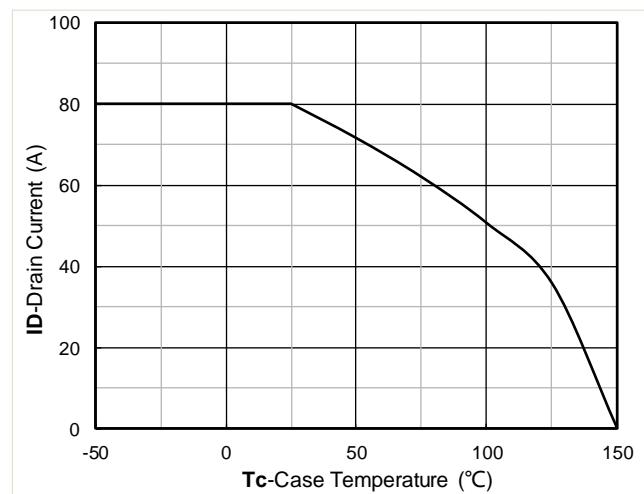


Figure 8. Maximum Continuous Drain Current vs Case Temperature

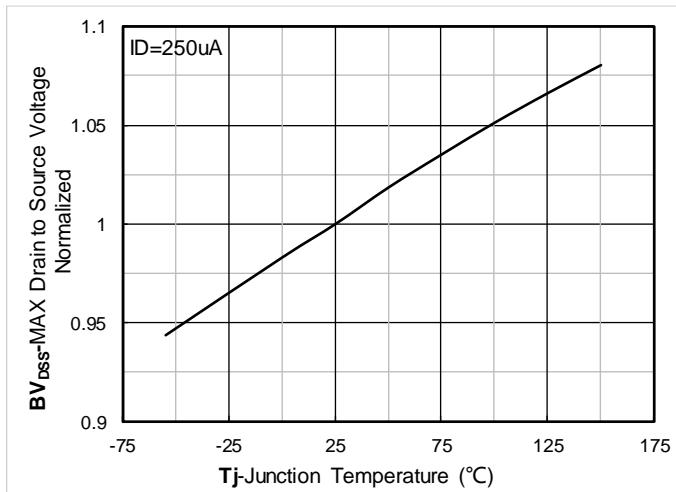


Figure 9. Normalized breakdown voltage

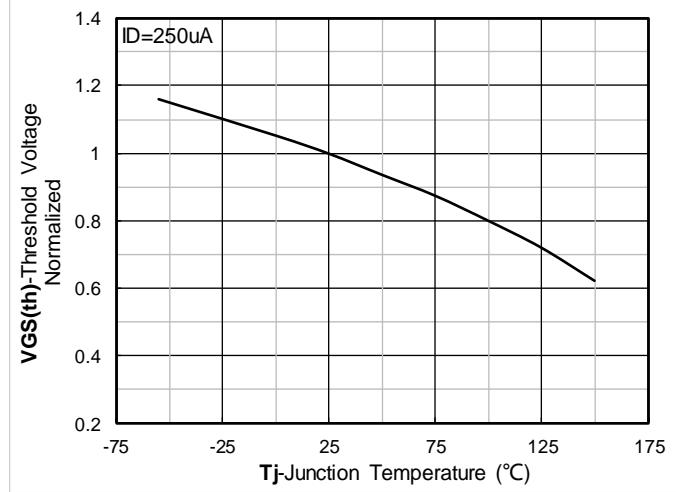


Figure 10. Normalized Threshold voltage

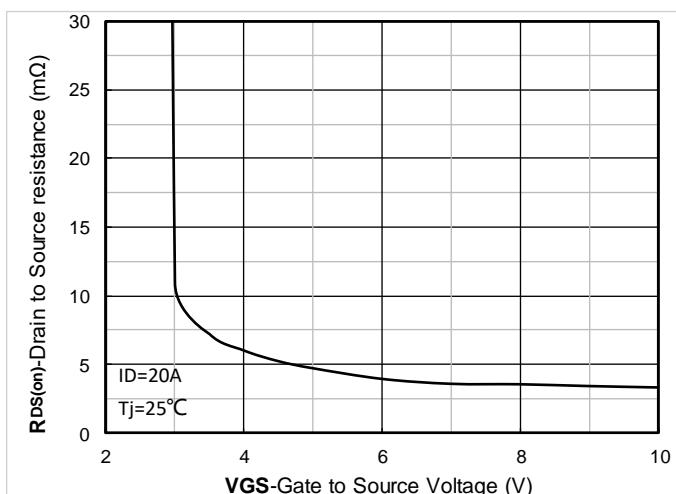


Figure 11. On-Resistance vs Gate to Source Voltage

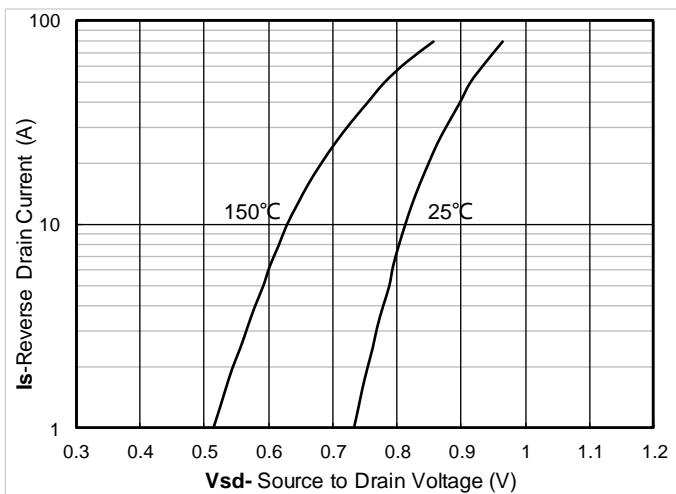


Figure 12. Forward characteristics of reverse diode

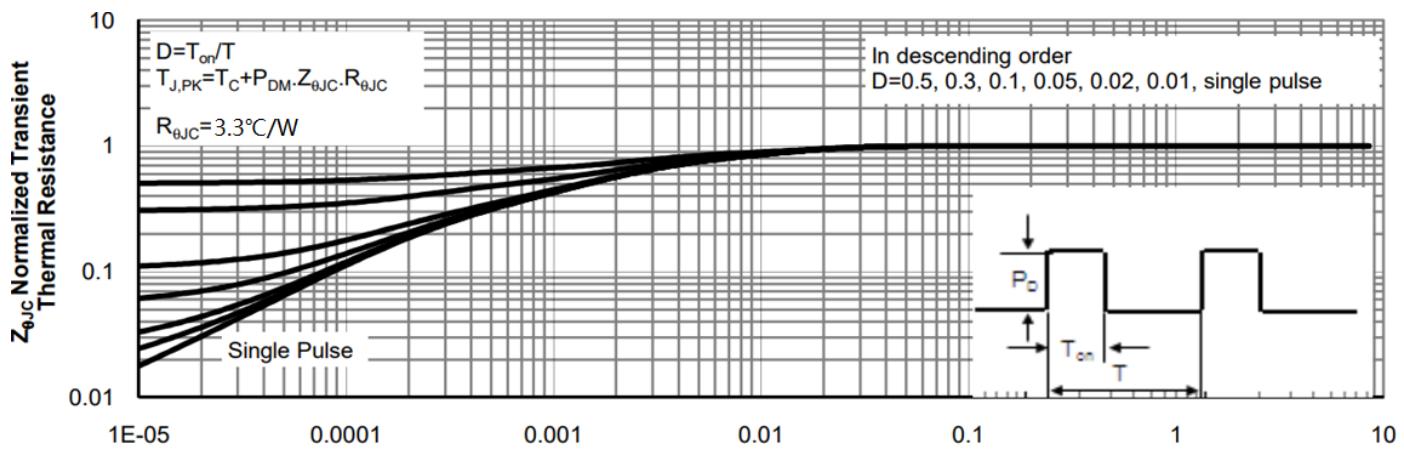
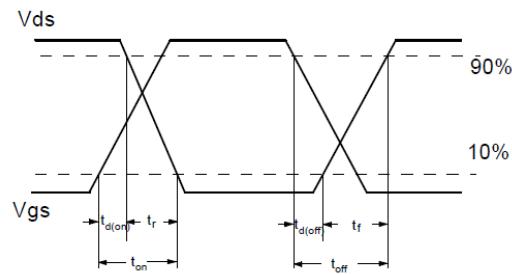
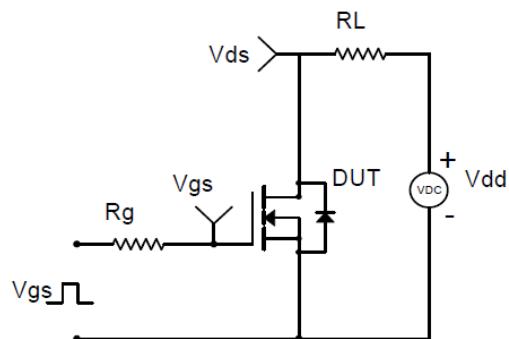
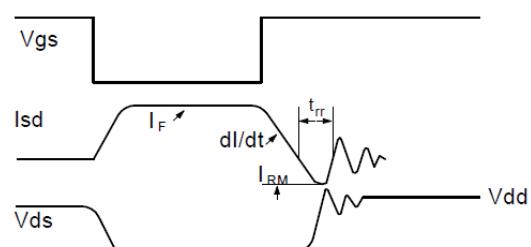
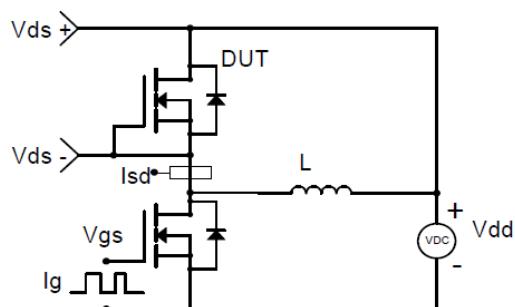


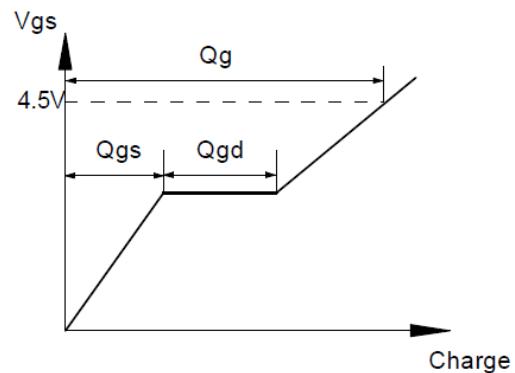
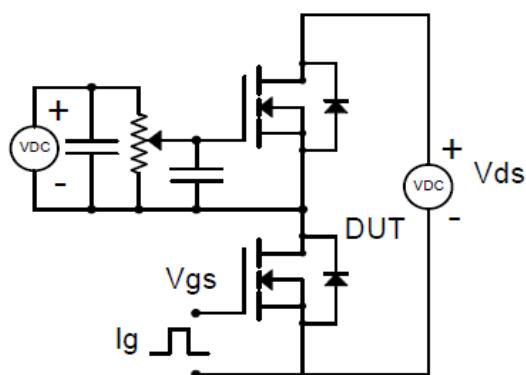
Figure 13. Normalized Maximum Transient Thermal Impedance



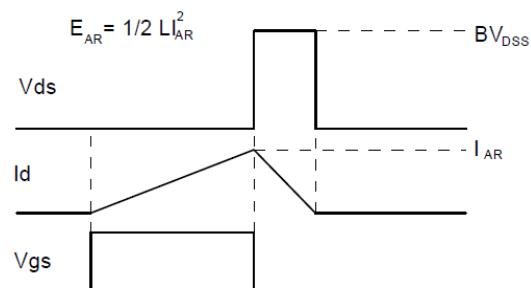
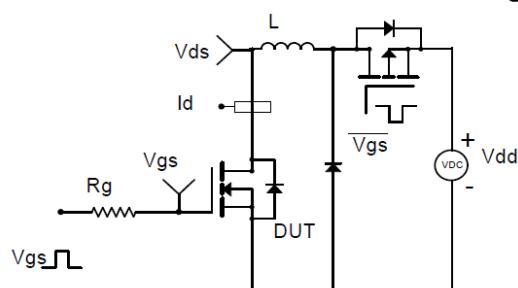
Resistive Switching Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms

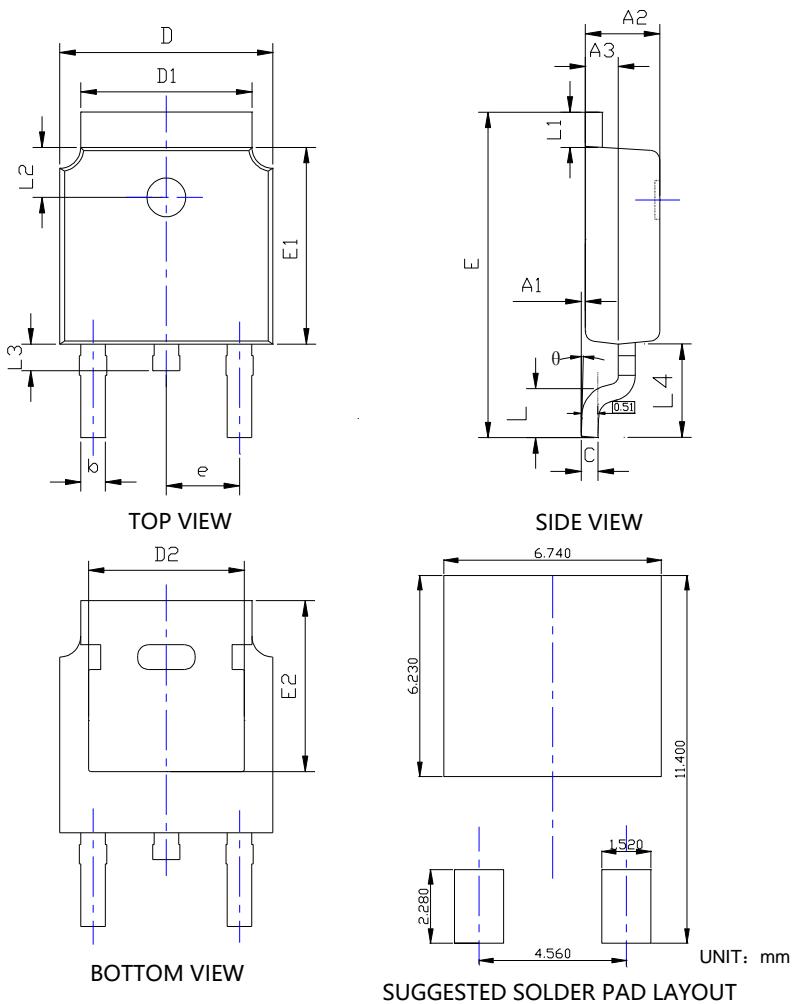


Gate Charge Test Circuit &amp; Waveform



Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms

## ■TO-252-B Package information



SYMBOL	DIMENSIONS			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.008	0.000	---	0.200
A2	0.087	0.091	0.094	2.200	2.300	2.400
A3	0.035	0.039	0.043	0.900	1.000	1.100
b	0.026	0.030	0.034	0.660	0.760	0.860
c	0.018	0.020	0.023	0.460	0.520	0.580
D	0.256	0.260	0.264	6.500	6.600	6.700
D1	0.203	0.209	0.215	5.150	5.300	5.450
D2	0.181	0.189	0.195	4.600	4.800	4.950
E	0.390	0.398	0.406	9.900	10.100	10.300
E1	0.236	0.240	0.244	6.000	6.100	6.200
E2	0.203	0.209	0.215	5.150	5.300	5.450
e	0.090BSC			2.286BSC		
L	0.049	0.059	0.069	1.250	1.500	1.750
L1	0.035	---	0.050	0.900	---	1.270
L2	0.055	---	0.075	1.400	---	1.900
L3	0.240	0.310	0.039	0.600	0.800	1.000
L4	0.114REF			2.900REF		
θ	0°	---	10°	0°	---	10°

### NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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